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|----------------------|--|
| Applications | Commercial Grade |
| Feature | No Directivity |
| | Multilayer |
| | Non-Magnetic Core (Dielectric Ceramic) High Self Resonant Frequency |
| Series Type | MLK |
| Status | EOL announced Recommended Alternate Part No. : MLG0603S15NJT000 (Interchangeability is not guaranteed.) |
| | Discontinue Issue Date : May.24, 2021 |
| | Last Purchase Order Date : Mar.31, 2026 |
| | Last Shipment Date : Jun.30, 2026 |
| Brand | TDK |



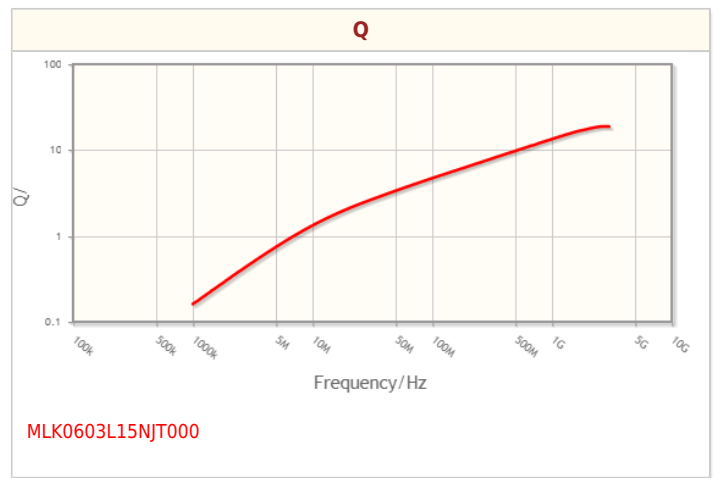
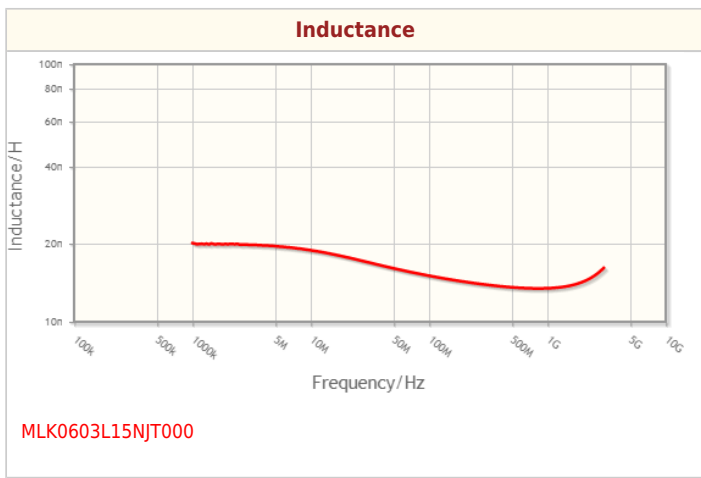
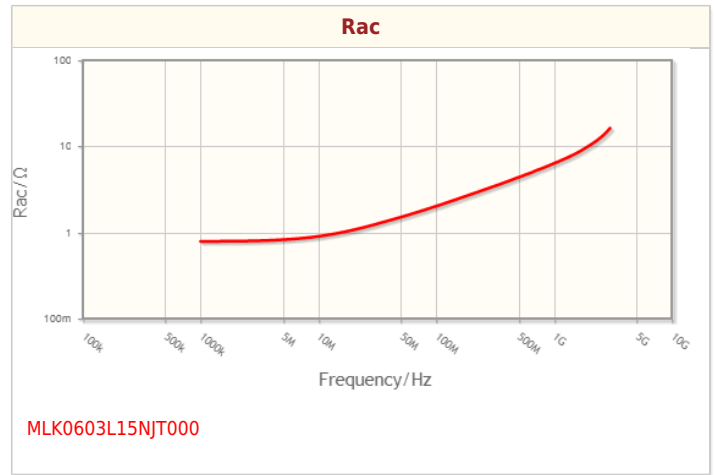
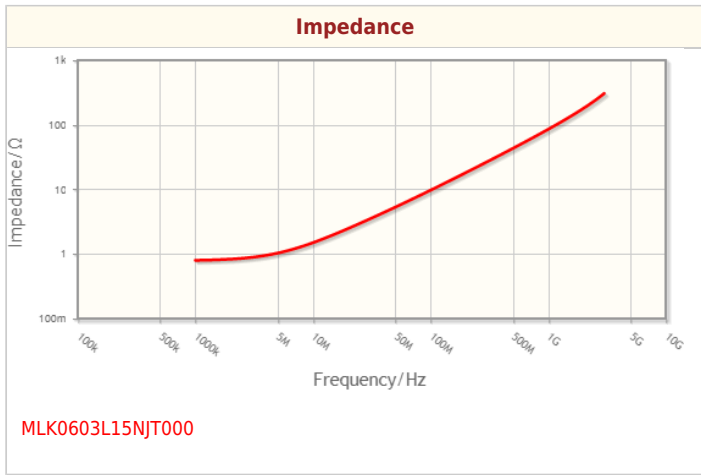
| Size | |
|------------------------------|----------------|
| Length(L) | 0.60mm ±0.03mm |
| Width(W) | 0.30mm ±0.03mm |
| Thickness Height | 0.30mm ±0.03mm |
| Recommended Land Pattern (A) | 0.25mm Nom. |
| Recommended Land Pattern (B) | 0.30mm Nom. |
| Recommended Land Pattern (C) | 0.30mm Nom. |

| Electrical Characteristics | |
|--------------------------------|--------------------|
| Inductance | 15nH ±5% at 100MHz |
| Rated Current | 150mA |
| DC Resistance [Typ.] | 660mΩ |
| DC Resistance [Max.] | 1.1Ω |
| Self Resonant Frequency [Min.] | 4.5GHz |
| Self Resonant Frequency [Typ.] | 6.6GHz |
| Q [Min.] | 6 at 300MHz |
| Q [Typ.] | 8 at 300MHz |

| Other | |
|---|--|
| Operating Temp. Range (Including Self-Temp. Rise) | -55 to 125°C |
| Soldering Method | Reflow |
| | Iron Soldering |
| AEC-Q200 | NO |
| Packing | Punched (Paper)Taping [180mm Reel, Tape width 8mm] |
| Package Quantity | 15000pcs |
| Weight | 0.0002g |

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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Associated Images

